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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO	
09/844,347	04/27/2001	Jun Zeng	SE1645PD (50042)	2463	
75	590 06/18/2003				
CHRISTOPHER F. REGAN, ESQUIRE ALLEN, DYER, DOPPELT, MILBRATH & GILCHRIST, P.A. P.O. Box 3791			EXAMINER		
			SOWARD, IDA M		
Orlando, FL 3	2802-3791		ART UNIT	PAPER NUMBER	
			2822	<u> </u>	
			DATE MAILED: 06/18/2003		

Please find below and/or attached an Office communication concerning this application or proceeding.

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	,	Appli	cation No.	Applicant(s)	
			14,347	ZENG, JUN	
Office Action Summary		Exam	iner	Art Unit	
			Soward	2822	
Period fo	The MAILING DATE of this commu r Reply	nication appears o	n the cover sheet	with the correspondence ad	ldress
THE I - Exter after - If the - If NO - Failu - Any r	ORTENED STATUTORY PERIOD IN MAILING DATE OF THIS COMMUN IN SIGNS of time may be available under the provision SIX (6) MONTHS from the mailing date of this comperiod for reply specified above is less than thirty (period for reply is specified above, the maximum set to reply within the set or extended period for repleply received by the Office later than three months and patent term adjustment. See 37 CFR 1.704(b).	IICATION. s of 37 CFR 1.136(a). In munication. 30) days, a reply within th statutory period will apply a v will. by statute. cause th	no event, however, may e statutory minimum of the and will expire SIX (6) Mode application to become	a reply be timely filed nirty (30) days will be considered timel DNTHS from the mailing date of this of ABANDONED (35 U.S.C. § 133).	y. ommunication.
1)⊠	Responsive to communication(s) f	iled on <u>31 March 2</u>	<u> 2003</u> .		
2a)⊠	This action is FINAL.	2b) This action	on is non-final.		
3)□ Dispositi	Since this application is in condition closed in accordance with the praction of Claims	on for allowance ex ctice under <i>Ex par</i>	cept for formal m te Quayle, 1935 (natters, prosecution as to the C.D. 11, 453 O.G. 213.	ne merits is
4)⊠	Claim(s) 23-39 is/are pending in the	e application.		-	
	4a) Of the above claim(s) is/s	are withdrawn fron	n consideration.		
5)	Claim(s) is/are allowed.				
6)🖂	Claim(s) <u>23-39</u> is/are rejected.				
7)	Claim(s) is/are objected to.				
•	Claim(s) are subject to restr	iction and/or electi	on requirement.		
	on Papers				
,—	The specification is objected to by the				
10)[_]	The drawing(s) filed on is/are				
	Applicant may not request that any ol	•	•	•	
11)	The proposed drawing correction file			disapproved by the Examin	er.
42)□:	If approved, corrected drawings are re The oath or declaration is objected t				
•		o by the Examine	•		
-	inder 35 U.S.C. §§ 119 and 120	- farfarainn meiarit	huundar 25 tt S.C	5 5 110(a) (d) or (f)	
•	Acknowledgment is made of a clair	n for foreign prioni	ty under 35 0.5.C	. 9 119(a)-(u) or (i).	
a)	All b) Some * c) None of:	, documents have	boon received		
	1. Certified copies of the priority			Application No.	
	2. Certified copies of the priority				Stane
* 8	3. Copies of the certified copies application from the Intersee the attached detailed Office acti	national Bureau (f	PCT Rule 17.2(a)).	otage
14) 🗌 A	Acknowledgment is made of a claim	for domestic priori	ity under 35 U.S.0	C. § 119(e) (to a provisiona	l application).
)				
Attachmen	t(s)				
2) Notic	e of References Cited (PTO-892) e of Draftsperson's Patent Drawing Review (mation Disclosure Statement(s) (PTO-1449)			w Summary (PTO-413) Paper No of Informal Patent Application (PT	
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DETAILED ACTION

This Office Action is in response to the Applicant's amendment filed March 31, 2003.

Claim Rejections - 35 USC § 102

The following is a quotation of the appropriate paragraphs of 35 U.S.C. 102 that form the basis for the rejections under this section made in this Office action:

A person shall be entitled to a patent unless -

(a) the invention was known or used by others in this country, or patented or described in a printed publication in this or a foreign country, before the invention thereof by the applicant for a patent.

Claims 23-24 are rejected under 35 U.S.C. 102(a) as being anticipated by Admitted Prior Art Figures 1 and 3a-3b.

Prior Art Figures 1 and 3a-3b teach a semiconductor layer 9 having a trench 14 therein; a gate dielectric layer 24 lining the trench; a gate conducting layer 12 in a lower potion of the trench; a dielectric layer 20 in an upper portion of the trench and extending outwardly from the semiconductor layer; source regions 26 adjacent the outwardly extending dielectric layer; source/body contact regions 18 laterally spaced from the gate conducting layer and non-interruptibly contacting the source regions; and a source electrode 22 on the source regions and on the dielectric layer.

Claim Rejections - 35 USC § 103

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The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all obviousness rejections set forth in this Office action:

(a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the invention was made to a person having ordinary skill in the art to which said subject matter pertains. Patentability shall not be negatived by the manner in which the invention was made.

Claims 25, 27, 32 and 36-37 are rejected under 35 U.S.C. 103(a) as being unpatentable over Prior Art Figures 1 and 3a-3b as applied to claims 23-24 above, and further in view of Gilbert et al. (5,349,224).

Prior Art Figures 1 and 3a-3b teach all mentioned in the rejection above. Prior Art Figures 1 and 3a-3b further teach a source electrode 22 on the source regions 26, on the dielectric layer 20, and on the source/body contact regions 18; a gate dielectric layer 24 lining the trench. However, Prior Art Figures 1 and 3a-3b fail to teach at least one conductive via between the source electrode and the source/body contact region. Gilbert et al. teach at least one conductive via between the source electrode 90 and the source/body contact region 64 (Figure 5F). Gilbert et al. further teach the source electrode on the source region, on the dielectric layer and on the conductive via; and an opening exposing the source/body contact region, wherein the source/body contact regions are exposed by an opening in the source region (Figure 5F). Therefore, it would have been obvious to one having ordinary skill in the art at the time the invention was made to modify the MOSFET of Prior Art Figures 1 and 3a-3b and with the MOSFET having conductive vias of Gilbert et al. to be readily integrable in a semiconductor integrated circuit (col. 1, lines 6-11).

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Claims 26, 30 and 33 are rejected under 35 U.S.C. 103(a) as being unpatentable over Prior Art Figures 1 and 3a-3b and Gilbert et al. (5,349,224) as applied to claims 23-24 above, and further in view of Grabowski et al. (6,140,678).

Prior Art Figures 1 and 3a-3b and Gilbert et al. teach all mentioned in the rejections above. However, Prior Art Figures 1 and 3a-3b and Gilbert et al. fail to teach a recess over the source/body contact regions wherein the source/body contact regions are recessed within the semiconductor layer adjacent the source regions. Grabowski et al. teach a recess over the source/body contact regions 33 wherein the source/body contact regions are recessed within the semiconductor layer 14 adjacent the source regions 34 (Figure 4A). Therefore, it would have been obvious to one having ordinary skill in the art at the time the invention was made to modify the MOSFET of Prior Art Figures 1 and 3a-3b and MOSFET having conductive vias of Gilbert et al. with the MOSFET having recessed areas of Grabowski et al. to reduce hot carrier injection (col. 1, lines 46-65).

Claim 29, 31, 35 and 39 are rejected under 35 U.S.C. 103(a) as being unpatentable over Prior Art Figures 1 and 3a-3b and Gilbert et al. (5,349,224) as applied to claim 23-24 above, and further in view of Shih et al. (5,283,452).

Prior Art Figures 1 and 3a-3b and Gilbert et al. teach all mentioned in the rejections above. However, Prior Art Figures 1 and 3a-3b and Gilbert et al. fail to teach a gate recess depth within a range of 0.2 to 0.8 microns. Shih et al. teach a gate recess depth of 0.25 microns (col. 5, lines 67-68). In regard to claim 31, since Shih et al. teach

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an optimal gate recess depth of 0.25 microns, it is within the art of ordinary skill to provide an upper surface of the recess of less than 1 micron. Therefore, it would have been obvious to one having ordinary skill in the art at the time the invention was made to modify the MOSFET of Prior Art Figures 1 and 3a-3b and the MOSFET having conductive vias of Gilbert et al. with the FET having the gate recess depth of Shih et al. to achieve high power operation (col. 61-68).

Claims 28, 34 and 38 are rejected under 35 U.S.C. 103(a) as being unpatentable over Prior Art Figures 1 and 3a-3b and Gilbert et al. (5,349,224) as applied to claim 23-24 above, and further in view of Singh et al. (5,960,311).

Prior Art Figures 1 and 3a-3b and Gilbert et al. teach all mentioned in the rejections above. However, Prior Art Figures 1 and 3a-3b and Gilbert et al. fail to teach a dielectric layer extending from a region equal to or less than about 1 micron. Singh et al. teach a dielectric layer extending from a region from 0.5 to 1.2 microns (col. 5, lines 21-26). Therefore, it would have been obvious to one having ordinary skill in the art at the time the invention was made to modify the MOSFET of Prior Art Figures 1 and 3a-3b and the MOSFET having conductive vias of Gilbert et al. with the MOSFET having a dielectric layer extending from a region of Singh et al. to increase the speed of integrated circuits (col. 3, lines 33-36).

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Response to Arguments

Applicant's arguments filed 03-31-03 have been fully considered but they are not persuasive.

Admitted Prior Art Figures 3a-3b disclose a dielectric layer 20 in an upper portion of the trench 14 and extending outwardly from the semiconductor layer 16, the outwardly extending dielectric layer having sidewalls aligned with sidewalls of the trench.

Conclusion

THIS ACTION IS MADE FINAL. Applicant is reminded of the extension of time policy as set forth in 37 CFR 1.136(a).

A shortened statutory period for reply to this final action is set to expire THREE MONTHS from the mailing date of this action. In the event a first reply is filed within TWO MONTHS of the mailing date of this final action and the advisory action is not mailed until after the end of the THREE-MONTH shortened statutory period, then the shortened statutory period will expire on the date the advisory action is mailed, and any extension fee pursuant to 37 CFR 1.136(a) will be calculated from the mailing date of the advisory action. In no event, however, will the statutory period for reply expire later than SIX MONTHS from the mailing date of this final action.

Any inquiry concerning this communication or earlier communications from the examiner should be directed to Ida M Soward whose telephone number is 703-305Application/Control Number: 09/844,347

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3308. The examiner can normally be reached on Monday - Thursday, 6:30 am to 7:00

pm.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's

supervisor, Amir Zarabian can be reached on 703-308-4905. The fax phone numbers

for the organization where this application or proceeding is assigned are 703-872-9318

for regular communications and 703-308-9319 for After Final communications.

Any inquiry of a general nature or relating to the status of this application or

proceeding should be directed to the receptionist whose telephone number is 703-308-

0956.

ims

June 12, 2003

AMIR ZARABIAN
SUPERVISORY PATENT EXAMINER
TECHNOLOGY CENTER 2800

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